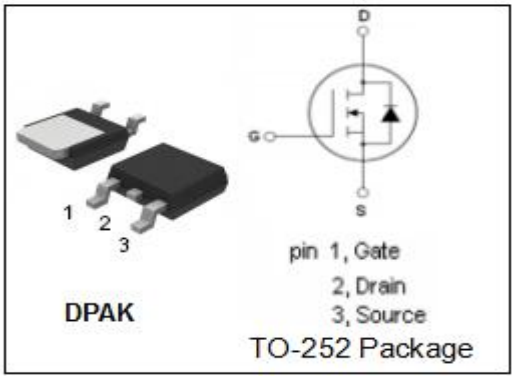
isc N-Channel MOSFET Transistor IPD50R800CE,IIPD50R800CE



• FEATURES

- Static drain-source on-resistance:
  $R_{DS(on)} \leqslant 800m\Omega$
- Enhancement mode:
- 100% avalanche tested
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

• DESCRITION

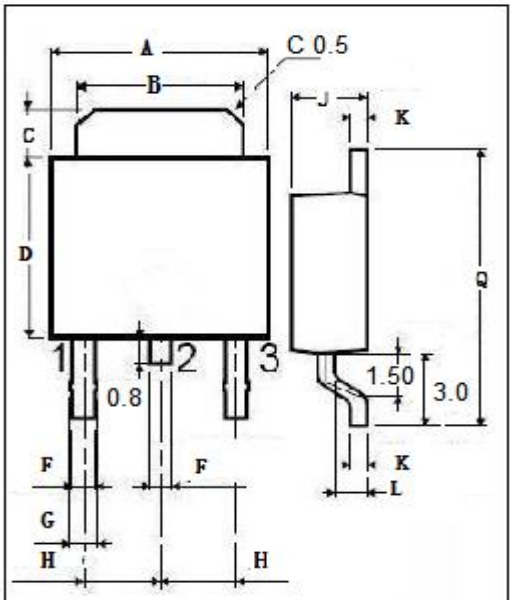
- Fast switching

• ABSOLUTE MAXIMUM RATINGS(T_a=25℃)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage	500	V
V_{GS}	Gate-Source Voltage	±20	V
I_D	Drain Current-Continuous	7.6	A
I_{DM}	Drain Current-Single Pulsed	15.5	A
P_D	Total Dissipation @T_C=25℃	60	W
T_j	Max. Operating Junction Temperature	150	℃
T_{stg}	Storage Temperature	-55~150	℃

• THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
Rth(j-c)	Channel-to-case thermal resistance	2.07	℃/W
Rth(j-a)	Channel-to-ambient thermal resistance	62	℃/W



DIM	mm MIN	MAX
A	6.40	6.60
B	5.20	5.40
C	1.15	1.35
D	5.70	6.10
F	0.65	
G	0.75	
H	2.10	2.50
J	2.10	2.40
K	0.40	0.60
L	0.90	1.10
Q	9.90	10.1

isc N-Channel MOSFET Transistor IPD50R800CE,IIPD50R800CE

ELECTRICAL CHARACTERISTICS

T_C=25℃ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V; I_D=1mA	500			V
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}; I_D=0.13μA	2.5		3.5	V
$R_{DS(on)}$	Drain-Source On-Resistance	V_{GS}=13V; I_D=1.3A			800	mΩ
I_{GSS}	Gate-Source Leakage Current	V_{GS}=20V			0.1	μA
I_{DSS}	Drain-Source Leakage Current	V_{DS}=500V; V_{GS}= 0V			1	μA
V_{SD}	Diode forward voltage	I_F=1.9A, V_{GS} = 0V		0.83		V